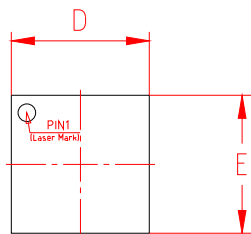
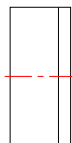


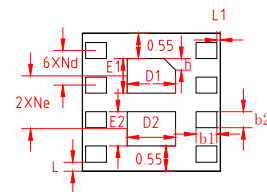
TOP VIEW
正视图



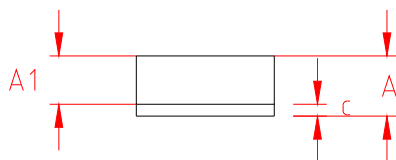
SIDE VIEW
侧视图




BOTTOM VIEW
背视图



SIDE VIEW
侧视图



机械尺寸/mm			
字符 SYMBOL	最小值 MIN	典型值 NOMINAL	最大值 MAX
A	0.700	0.750	0.800
A1	0.497	0.547	0.597
b1	0.400	0.450	0.500
b2	0.300	0.350	0.400
c	0.203 REF		
D	2.900	3.000	3.100
D1	1.000	1.050	1.100
D2	1.000	1.050	1.100
Nd	0.750BSC		
Ne	1.150BSC		
E	2.900	3.000	3.100
E1	0.700	0.750	0.800
E2	0.700	0.750	0.800
L	0.150	0.200	0.250
L1	0.070	0.075	0.080
h	C=0.250X45°		

 池州华宇电子科技股份有限公司 CHI ZHOU HISEMI ELECTRONICS TECHNOLOGY CO.,LTD				制图: Draw	NINGLIN 2024. 2. 7
HY-POD-LGA0013				制图核查: Drawing review	
PACKAGE OUTLINE DIMENSIONS LGA8 (3×3×0.75-P0.75)				审核: Checker	
页数 page	单位 unit	比例 scale	视图 view	核准: Approved	
	mm	1:1	